

Global Power Module Packaging Supply, Demand and Key Producers, 2026-2032

<https://marketpublishers.com/r/GCE9B4E455CEEN.html>

Date: August 2026

Pages: 231

Price: US\$ 4,480.00 (Single User License)

ID: GCE9B4E455CEEN

Abstracts

The global Power Module Packaging market size is expected to reach \$ 24670 million by 2032, rising at a market growth of 12.0% CAGR during the forecast period (2026-2032).

Power semiconductor module packaging is a critical manufacturing process that converts power semiconductor dies into electrically insulated, thermally efficient and mechanically robust power modules. It integrates IGBTs, SiC MOSFETs, SiC diodes, FRDs, MOSFETs, thyristors and other power devices through die attach, soldering or silver sintering, wire/ribbon/copper-clip interconnection, DBC or AMB substrate integration, terminal assembly, gel filling or transfer molding, baseplate or cooler integration, electrical testing and reliability qualification. The core value of this process lies in reducing parasitic inductance and thermal resistance while improving electrical isolation, heat dissipation, power-cycling lifetime and system-level assembly efficiency. These packaged power modules are widely used in xEV traction inverters, on-board chargers, DC/DC converters, fast-charging systems, photovoltaic and energy-storage inverters, industrial drives, UPS, wind converters, rail traction, HVDC transmission and other high-power energy-conversion applications.

Power semiconductor module packaging is not a simple back-end assembly step but a system-enabling manufacturing platform that determines whether power semiconductor dies can operate reliably in high-voltage, high-current and thermally demanding applications. Traditional power modules based on silicon IGBTs, FRDs, diodes and thyristors have long served industrial drives, UPS, rail traction, wind, solar, HVDC and high-power conversion systems. The latest growth cycle is being driven by electric vehicles, 800V architectures, SiC traction inverters, high-power OBCs, fast charging and energy-storage converters. These applications require lower parasitic inductance,

lower thermal resistance, higher junction-temperature tolerance and more robust power-cycling reliability, pushing the industry toward silver sintering, copper ribbon or clip interconnect, double-sided cooling, molded modules, low-inductance layouts and advanced automotive-grade reliability validation.

From a supply perspective, the global market is structured around leading European, Japanese and U.S. IDMs and module specialists, fast-growing Chinese local suppliers and a group of OSATs entering power module packaging services. Companies such as Infineon, Mitsubishi Electric, Fuji Electric, STMicroelectronics, onsemi, ROHM, Bosch, Hitachi Energy and Semikron Danfoss have strong positions in module design, industrial and automotive qualification, high-voltage platforms and global customer access. In China, StarPower, CRRC Times Electric, BYD Semiconductor, MacMic, Silan Microelectronics, China Resources Microelectronics, Yangjie Technology and United Nova Technology are building scale in IGBT, SiC, IPM and automotive power modules. Meanwhile, Amkor, ASE, UTAC, Tongfu Microelectronics and Carsem are expanding from power discrete packaging into power modules, IPMs and wide-bandgap power packages. Because internal IDM packaging and customer-specific module programs are often not separately disclosed, the industry should be analyzed through separate layers: a broad longlist, a core formal list and a narrower revenue-model list.

From a demand perspective, electric vehicles represent the largest structural driver for advanced power module packaging. Traction inverters, OBCs, DC/DC converters and high-voltage charging architectures require power modules with higher power density, lower switching losses and stronger thermal performance. At the same time, photovoltaic and energy-storage inverters continue to support demand for industrial IGBT modules, three-level modules, Si/SiC hybrid modules and high-reliability joining processes. Industrial drives, UPS, wind converters, rail traction and HVDC systems remain less volatile but highly demanding end markets, requiring high-voltage, high-current and long-life module platforms. This demand structure explains why both high-volume automotive module suppliers and lower-volume, high-ASP high-power module specialists can coexist in the global supply chain.

From a regional perspective, Europe and Japan remain key centers for advanced module design, substrate integration, high-power platforms and reliability know-how. The U.S. maintains advantages in SiC devices, aerospace and defense-oriented modules and power packaging services, while China is rapidly expanding through EV demand, renewable energy deployment, rail traction, local substitution and vertically integrated power electronics supply chains. Policy support for semiconductor manufacturing, advanced packaging, electrification and supply-chain localization is

reinforcing regional investment. The U.S. CHIPS program, Japan's semiconductor revitalization initiatives and China's new-energy vehicle and power-infrastructure policies together create a favorable environment for continued investment in power semiconductor packaging capacity and technology upgrades.

Looking ahead, market growth will be driven less by unit volume alone and more by the increasing value content of advanced packaging. SiC modules, automotive traction modules, double-sided cooling structures, silver-sintered die attach, molded power modules, high-voltage modules and highly integrated IPMs will raise the average packaging value per module. However, the market will also face price pressure as SiC die costs fall, automotive customers push for localization and standard package platforms become more mature. Suppliers that combine module design, thermal-electrical-mechanical co-optimization, process automation, material-system control and customer co-development will be better positioned to defend margins. The likely competitive outcome is a two-layer structure: leading IDMs and module specialists remain dominant in premium automotive and high-voltage platforms, while OSATs and Chinese local suppliers gain share in industrial, renewable, OBC and selected automotive module programs.

This report studies the global Power Module Packaging production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Power Module Packaging and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Power Module Packaging that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Power Module Packaging total production and demand, 2021-2032, (K Units)

Global Power Module Packaging total production value, 2021-2032, (USD Million)

Global Power Module Packaging production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (K Units), (based on production site)

Global Power Module Packaging consumption by region & country, CAGR, 2021-2032 & (K Units)

U.S. VS China: Power Module Packaging domestic production, consumption, key domestic manufacturers and share

Global Power Module Packaging production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (K Units)

Global Power Module Packaging production by Module Type, production, value, CAGR, 2021-2032, (USD Million) & (K Units)

Global Power Module Packaging production by Application, production, value, CAGR, 2021-2032, (USD Million) & (K Units)

This report profiles key players in the global Power Module Packaging market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include STMicroelectronics, Infineon, Wolfspeed, Rohm, onsemi, BYD Semiconductor, Microchip (Microsemi), Mitsubishi Electric, Semikron Danfoss, Fuji Electric, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Power Module Packaging market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (K Units) and average price (US\$/Unit) by manufacturer, by Module Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Power Module Packaging Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Power Module Packaging Market, Segmentation by Module Type:

SiC MOSFET Module

IGBT Module

Intelligent Power Module (IPM)

Others

Global Power Module Packaging Market, Segmentation by Package Architecture:

Molded Power Module

Gel-filled Power Module

Global Power Module Packaging Market, Segmentation by Interconnection and Die Attach:

Solder Die Attach

Silver Sintering

Copper Sintering

Others

Global Power Module Packaging Market, Segmentation by Application:

Automotive & EV/HEV

Industrial Control

Consumer Appliances

Wind power, PV, Energy Storage

Traction

Military & Avionics

Others

Companies Profiled:

STMicroelectronics

Infineon

Wolfspeed

Rohm

onsemi

BYD Semiconductor

Microchip (Microsemi)

Mitsubishi Electric

Semikron Danfoss

Fuji Electric

Navitas (GeneSiC)

Toshiba

San'an Optoelectronics

Littelfuse

CETC 55

WeEn Semiconductors

BASiC Semiconductor

SemiQ

Diodes Incorporated

SanRex

Alpha & Omega Semiconductor

Bosch

GE Aerospace

KEC Corporation

PANJIT Group

Nexperia

Vishay Intertechnology

Zhuzhou CRRC Times Semiconductor

China Resources Microelectronics Limited

StarPower

Yangzhou Yangjie Electronic Technology

Guangdong AccoPower Semiconductor

Changzhou Galaxy Century Microelectronics

Hangzhou Silan Microelectronics

Cisoid

SK keyfoundry

PN Junction Semiconductor (Hangzhou)

United Nova Technology (UNT)

InventChip Technology (IVCT)

Leadrive Technology

HAIMOSIC (SHANGHAI)

Suzhou Sko Semiconductor

Shenzhen AST Technology

Suzhou Xizhi Technology

Archimedes Semiconductor (Hefei)

Grecon Semiconductor (Shanghai)

Hebei Sinopack Electronic Technology

Denso

GeePak

Hitachi Energy

Minebea Power Semiconductor Device

ZhiXin Semiconductor

NJSM Electronics

Hefei Cpower Technology

MacMic Science & Technology

Alkaidsemi

Key Questions Answered:

1. How big is the global Power Module Packaging market?
2. What is the demand of the global Power Module Packaging market?
3. What is the year over year growth of the global Power Module Packaging market?
4. What is the production and production value of the global Power Module Packaging market?
5. Who are the key producers in the global Power Module Packaging market?
6. What are the growth factors driving the market demand?

Contents

1 SUPPLY SUMMARY

- 1.1 Power Module Packaging Introduction
- 1.2 World Power Module Packaging Supply & Forecast
 - 1.2.1 World Power Module Packaging Production Value (2021 & 2025 & 2032)
 - 1.2.2 World Power Module Packaging Production (2021-2032)
 - 1.2.3 World Power Module Packaging Pricing Trends (2021-2032)
- 1.3 World Power Module Packaging Production by Region (Based on Production Site)
 - 1.3.1 World Power Module Packaging Production Value by Region (2021-2032)
 - 1.3.2 World Power Module Packaging Production by Region (2021-2032)
 - 1.3.3 World Power Module Packaging Average Price by Region (2021-2032)
 - 1.3.4 North America Power Module Packaging Production (2021-2032)
 - 1.3.5 Europe Power Module Packaging Production (2021-2032)
 - 1.3.6 China Power Module Packaging Production (2021-2032)
 - 1.3.7 Japan Power Module Packaging Production (2021-2032)
 - 1.3.8 South Korea Power Module Packaging Production (2021-2032)
- 1.4 Market Drivers, Restraints and Trends
 - 1.4.1 Power Module Packaging Market Drivers
 - 1.4.2 Factors Affecting Demand
 - 1.4.3 Power Module Packaging Major Market Trends

2 DEMAND SUMMARY

- 2.1 World Power Module Packaging Demand (2021-2032)
- 2.2 World Power Module Packaging Consumption by Region
 - 2.2.1 World Power Module Packaging Consumption by Region (2021-2026)
 - 2.2.2 World Power Module Packaging Consumption Forecast by Region (2027-2032)
- 2.3 United States Power Module Packaging Consumption (2021-2032)
- 2.4 China Power Module Packaging Consumption (2021-2032)
- 2.5 Europe Power Module Packaging Consumption (2021-2032)
- 2.6 Japan Power Module Packaging Consumption (2021-2032)
- 2.7 South Korea Power Module Packaging Consumption (2021-2032)
- 2.8 ASEAN Power Module Packaging Consumption (2021-2032)
- 2.9 India Power Module Packaging Consumption (2021-2032)

3 WORLD MANUFACTURERS COMPETITIVE ANALYSIS

- 3.1 World Power Module Packaging Production Value by Manufacturer (2021-2026)
- 3.2 World Power Module Packaging Production by Manufacturer (2021-2026)
- 3.3 World Power Module Packaging Average Price by Manufacturer (2021-2026)
- 3.4 Power Module Packaging Company Evaluation Quadrant
- 3.5 Industry Rank and Concentration Rate (CR)
 - 3.5.1 Global Power Module Packaging Industry Rank of Major Manufacturers
 - 3.5.2 Global Concentration Ratios (CR4) for Power Module Packaging in 2025
 - 3.5.3 Global Concentration Ratios (CR8) for Power Module Packaging in 2025
- 3.6 Power Module Packaging Market: Overall Company Footprint Analysis
 - 3.6.1 Power Module Packaging Market: Region Footprint
 - 3.6.2 Power Module Packaging Market: Company Product Type Footprint
 - 3.6.3 Power Module Packaging Market: Company Product Application Footprint
- 3.7 Competitive Environment
 - 3.7.1 Historical Structure of the Industry
 - 3.7.2 Barriers of Market Entry
 - 3.7.3 Factors of Competition
- 3.8 New Entrant and Capacity Expansion Plans
- 3.9 Mergers, Acquisition, Agreements, and Collaborations

4 UNITED STATES VS CHINA VS REST OF THE WORLD

- 4.1 United States VS China: Power Module Packaging Production Value Comparison
 - 4.1.1 United States VS China: Power Module Packaging Production Value Comparison (2021 & 2025 & 2032)
 - 4.1.2 United States VS China: Power Module Packaging Production Value Market Share Comparison (2021 & 2025 & 2032)
- 4.2 United States VS China: Power Module Packaging Production Comparison
 - 4.2.1 United States VS China: Power Module Packaging Production Comparison (2021 & 2025 & 2032)
 - 4.2.2 United States VS China: Power Module Packaging Production Market Share Comparison (2021 & 2025 & 2032)
- 4.3 United States VS China: Power Module Packaging Consumption Comparison
 - 4.3.1 United States VS China: Power Module Packaging Consumption Comparison (2021 & 2025 & 2032)
 - 4.3.2 United States VS China: Power Module Packaging Consumption Market Share Comparison (2021 & 2025 & 2032)
- 4.4 United States Based Power Module Packaging Manufacturers and Market Share, 2021-2026
 - 4.4.1 United States Based Power Module Packaging Manufacturers, Headquarters

and Production Site (States, Country)

4.4.2 United States Based Manufacturers Power Module Packaging Production Value (2021-2026)

4.4.3 United States Based Manufacturers Power Module Packaging Production (2021-2026)

4.5 China Based Power Module Packaging Manufacturers and Market Share

4.5.1 China Based Power Module Packaging Manufacturers, Headquarters and Production Site (Province, Country)

4.5.2 China Based Manufacturers Power Module Packaging Production Value (2021-2026)

4.5.3 China Based Manufacturers Power Module Packaging Production (2021-2026)

4.6 Rest of World Based Power Module Packaging Manufacturers and Market Share, 2021-2026

4.6.1 Rest of World Based Power Module Packaging Manufacturers, Headquarters and Production Site (State, Country)

4.6.2 Rest of World Based Manufacturers Power Module Packaging Production Value (2021-2026)

4.6.3 Rest of World Based Manufacturers Power Module Packaging Production (2021-2026)

5 MARKET ANALYSIS BY MODULE TYPE

5.1 World Power Module Packaging Market Size Overview by Module Type: 2021 VS 2025 VS 2032

5.2 Segment Introduction by Module Type

5.2.1 SiC MOSFET Module

5.2.2 IGBT Module

5.2.3 Intelligent Power Module (IPM)

5.2.4 Others

5.3 Market Segment by Module Type

5.3.1 World Power Module Packaging Production by Module Type (2021-2032)

5.3.2 World Power Module Packaging Production Value by Module Type (2021-2032)

5.3.3 World Power Module Packaging Average Price by Module Type (2021-2032)

6 MARKET ANALYSIS BY PACKAGE ARCHITECTURE

6.1 World Power Module Packaging Market Size Overview by Package Architecture: 2021 VS 2025 VS 2032

6.2 Segment Introduction by Package Architecture

6.2.1 Molded Power Module

6.2.2 Gel-filled Power Module

6.3 Market Segment by Package Architecture

6.3.1 World Power Module Packaging Production by Package Architecture
(2021-2032)

6.3.2 World Power Module Packaging Production Value by Package Architecture
(2021-2032)

6.3.3 World Power Module Packaging Average Price by Package Architecture
(2021-2032)

7 MARKET ANALYSIS BY INTERCONNECTION AND DIE ATTACH

7.1 World Power Module Packaging Market Size Overview by Interconnection and Die Attach: 2021 VS 2025 VS 2032

7.2 Segment Introduction by Interconnection and Die Attach

7.2.1 Solder Die Attach

7.2.2 Silver Sintering

7.2.3 Copper Sintering

7.2.4 Others

7.3 Market Segment by Interconnection and Die Attach

7.3.1 World Power Module Packaging Production by Interconnection and Die Attach
(2021-2032)

7.3.2 World Power Module Packaging Production Value by Interconnection and Die Attach
(2021-2032)

7.3.3 World Power Module Packaging Average Price by Interconnection and Die Attach
(2021-2032)

8 MARKET ANALYSIS BY APPLICATION

8.1 World Power Module Packaging Market Size Overview by Application: 2021 VS 2025 VS 2032

8.2 Segment Introduction by Application

8.2.1 Automotive & EV/HEV

8.2.2 Industrial Control

8.2.3 Consumer Appliances

8.2.4 Wind power, PV, Energy Storage

8.2.5 Traction

8.2.6 Military & Avionics

8.2.7 Others

8.3 Market Segment by Application

8.3.1 World Power Module Packaging Production by Application (2021-2032)

8.3.2 World Power Module Packaging Production Value by Application (2021-2032)

8.3.3 World Power Module Packaging Average Price by Application (2021-2032)

9 COMPANY PROFILES

9.1 STMicroelectronics

9.1.1 STMicroelectronics Details

9.1.2 STMicroelectronics Major Business

9.1.3 STMicroelectronics Power Module Packaging Product and Services

9.1.4 STMicroelectronics Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.1.5 STMicroelectronics Recent Developments/Updates

9.1.6 STMicroelectronics Competitive Strengths & Weaknesses

9.2 Infineon

9.2.1 Infineon Details

9.2.2 Infineon Major Business

9.2.3 Infineon Power Module Packaging Product and Services

9.2.4 Infineon Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.2.5 Infineon Recent Developments/Updates

9.2.6 Infineon Competitive Strengths & Weaknesses

9.3 Wolfspeed

9.3.1 Wolfspeed Details

9.3.2 Wolfspeed Major Business

9.3.3 Wolfspeed Power Module Packaging Product and Services

9.3.4 Wolfspeed Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.3.5 Wolfspeed Recent Developments/Updates

9.3.6 Wolfspeed Competitive Strengths & Weaknesses

9.4 Rohm

9.4.1 Rohm Details

9.4.2 Rohm Major Business

9.4.3 Rohm Power Module Packaging Product and Services

9.4.4 Rohm Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.4.5 Rohm Recent Developments/Updates

9.4.6 Rohm Competitive Strengths & Weaknesses

9.5 onsemi

9.5.1 onsemi Details

9.5.2 onsemi Major Business

9.5.3 onsemi Power Module Packaging Product and Services

9.5.4 onsemi Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.5.5 onsemi Recent Developments/Updates

9.5.6 onsemi Competitive Strengths & Weaknesses

9.6 BYD Semiconductor

9.6.1 BYD Semiconductor Details

9.6.2 BYD Semiconductor Major Business

9.6.3 BYD Semiconductor Power Module Packaging Product and Services

9.6.4 BYD Semiconductor Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.6.5 BYD Semiconductor Recent Developments/Updates

9.6.6 BYD Semiconductor Competitive Strengths & Weaknesses

9.7 Microchip (Microsemi)

9.7.1 Microchip (Microsemi) Details

9.7.2 Microchip (Microsemi) Major Business

9.7.3 Microchip (Microsemi) Power Module Packaging Product and Services

9.7.4 Microchip (Microsemi) Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.7.5 Microchip (Microsemi) Recent Developments/Updates

9.7.6 Microchip (Microsemi) Competitive Strengths & Weaknesses

9.8 Mitsubishi Electric

9.8.1 Mitsubishi Electric Details

9.8.2 Mitsubishi Electric Major Business

9.8.3 Mitsubishi Electric Power Module Packaging Product and Services

9.8.4 Mitsubishi Electric Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.8.5 Mitsubishi Electric Recent Developments/Updates

9.8.6 Mitsubishi Electric Competitive Strengths & Weaknesses

9.9 Semikron Danfoss

9.9.1 Semikron Danfoss Details

9.9.2 Semikron Danfoss Major Business

9.9.3 Semikron Danfoss Power Module Packaging Product and Services

9.9.4 Semikron Danfoss Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.9.5 Semikron Danfoss Recent Developments/Updates

- 9.9.6 Semikron Danfoss Competitive Strengths & Weaknesses
- 9.10 Fuji Electric
 - 9.10.1 Fuji Electric Details
 - 9.10.2 Fuji Electric Major Business
 - 9.10.3 Fuji Electric Power Module Packaging Product and Services
 - 9.10.4 Fuji Electric Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.10.5 Fuji Electric Recent Developments/Updates
 - 9.10.6 Fuji Electric Competitive Strengths & Weaknesses
- 9.11 Navitas (GeneSiC)
 - 9.11.1 Navitas (GeneSiC) Details
 - 9.11.2 Navitas (GeneSiC) Major Business
 - 9.11.3 Navitas (GeneSiC) Power Module Packaging Product and Services
 - 9.11.4 Navitas (GeneSiC) Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.11.5 Navitas (GeneSiC) Recent Developments/Updates
 - 9.11.6 Navitas (GeneSiC) Competitive Strengths & Weaknesses
- 9.12 Toshiba
 - 9.12.1 Toshiba Details
 - 9.12.2 Toshiba Major Business
 - 9.12.3 Toshiba Power Module Packaging Product and Services
 - 9.12.4 Toshiba Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.12.5 Toshiba Recent Developments/Updates
 - 9.12.6 Toshiba Competitive Strengths & Weaknesses
- 9.13 San'an Optoelectronics
 - 9.13.1 San'an Optoelectronics Details
 - 9.13.2 San'an Optoelectronics Major Business
 - 9.13.3 San'an Optoelectronics Power Module Packaging Product and Services
 - 9.13.4 San'an Optoelectronics Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.13.5 San'an Optoelectronics Recent Developments/Updates
 - 9.13.6 San'an Optoelectronics Competitive Strengths & Weaknesses
- 9.14 Littelfuse
 - 9.14.1 Littelfuse Details
 - 9.14.2 Littelfuse Major Business
 - 9.14.3 Littelfuse Power Module Packaging Product and Services
 - 9.14.4 Littelfuse Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

- 9.14.5 Littelfuse Recent Developments/Updates
- 9.14.6 Littelfuse Competitive Strengths & Weaknesses
- 9.15 CETC
 - 9.15.1 CETC 55 Details
 - 9.15.2 CETC 55 Major Business
 - 9.15.3 CETC 55 Power Module Packaging Product and Services
 - 9.15.4 CETC 55 Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.15.5 CETC 55 Recent Developments/Updates
 - 9.15.6 CETC 55 Competitive Strengths & Weaknesses
- 9.16 WeEn Semiconductors
 - 9.16.1 WeEn Semiconductors Details
 - 9.16.2 WeEn Semiconductors Major Business
 - 9.16.3 WeEn Semiconductors Power Module Packaging Product and Services
 - 9.16.4 WeEn Semiconductors Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.16.5 WeEn Semiconductors Recent Developments/Updates
 - 9.16.6 WeEn Semiconductors Competitive Strengths & Weaknesses
- 9.17 BASiC Semiconductor
 - 9.17.1 BASiC Semiconductor Details
 - 9.17.2 BASiC Semiconductor Major Business
 - 9.17.3 BASiC Semiconductor Power Module Packaging Product and Services
 - 9.17.4 BASiC Semiconductor Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.17.5 BASiC Semiconductor Recent Developments/Updates
 - 9.17.6 BASiC Semiconductor Competitive Strengths & Weaknesses
- 9.18 SemiQ
 - 9.18.1 SemiQ Details
 - 9.18.2 SemiQ Major Business
 - 9.18.3 SemiQ Power Module Packaging Product and Services
 - 9.18.4 SemiQ Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.18.5 SemiQ Recent Developments/Updates
 - 9.18.6 SemiQ Competitive Strengths & Weaknesses
- 9.19 Diodes Incorporated
 - 9.19.1 Diodes Incorporated Details
 - 9.19.2 Diodes Incorporated Major Business
 - 9.19.3 Diodes Incorporated Power Module Packaging Product and Services
 - 9.19.4 Diodes Incorporated Power Module Packaging Production, Price, Value, Gross

Margin and Market Share (2021-2026)

9.19.5 Diodes Incorporated Recent Developments/Updates

9.19.6 Diodes Incorporated Competitive Strengths & Weaknesses

9.20 SanRex

9.20.1 SanRex Details

9.20.2 SanRex Major Business

9.20.3 SanRex Power Module Packaging Product and Services

9.20.4 SanRex Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.20.5 SanRex Recent Developments/Updates

9.20.6 SanRex Competitive Strengths & Weaknesses

9.21 Alpha & Omega Semiconductor

9.21.1 Alpha & Omega Semiconductor Details

9.21.2 Alpha & Omega Semiconductor Major Business

9.21.3 Alpha & Omega Semiconductor Power Module Packaging Product and Services

9.21.4 Alpha & Omega Semiconductor Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.21.5 Alpha & Omega Semiconductor Recent Developments/Updates

9.21.6 Alpha & Omega Semiconductor Competitive Strengths & Weaknesses

9.22 Bosch

9.22.1 Bosch Details

9.22.2 Bosch Major Business

9.22.3 Bosch Power Module Packaging Product and Services

9.22.4 Bosch Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.22.5 Bosch Recent Developments/Updates

9.22.6 Bosch Competitive Strengths & Weaknesses

9.23 GE Aerospace

9.23.1 GE Aerospace Details

9.23.2 GE Aerospace Major Business

9.23.3 GE Aerospace Power Module Packaging Product and Services

9.23.4 GE Aerospace Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.23.5 GE Aerospace Recent Developments/Updates

9.23.6 GE Aerospace Competitive Strengths & Weaknesses

9.24 KEC Corporation

9.24.1 KEC Corporation Details

9.24.2 KEC Corporation Major Business

- 9.24.3 KEC Corporation Power Module Packaging Product and Services
- 9.24.4 KEC Corporation Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
- 9.24.5 KEC Corporation Recent Developments/Updates
- 9.24.6 KEC Corporation Competitive Strengths & Weaknesses
- 9.25 PANJIT Group
 - 9.25.1 PANJIT Group Details
 - 9.25.2 PANJIT Group Major Business
 - 9.25.3 PANJIT Group Power Module Packaging Product and Services
 - 9.25.4 PANJIT Group Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.25.5 PANJIT Group Recent Developments/Updates
 - 9.25.6 PANJIT Group Competitive Strengths & Weaknesses
- 9.26 Nexperia
 - 9.26.1 Nexperia Details
 - 9.26.2 Nexperia Major Business
 - 9.26.3 Nexperia Power Module Packaging Product and Services
 - 9.26.4 Nexperia Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.26.5 Nexperia Recent Developments/Updates
 - 9.26.6 Nexperia Competitive Strengths & Weaknesses
- 9.27 Vishay Intertechnology
 - 9.27.1 Vishay Intertechnology Details
 - 9.27.2 Vishay Intertechnology Major Business
 - 9.27.3 Vishay Intertechnology Power Module Packaging Product and Services
 - 9.27.4 Vishay Intertechnology Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.27.5 Vishay Intertechnology Recent Developments/Updates
 - 9.27.6 Vishay Intertechnology Competitive Strengths & Weaknesses
- 9.28 Zhuzhou CRRC Times Semiconductor
 - 9.28.1 Zhuzhou CRRC Times Semiconductor Details
 - 9.28.2 Zhuzhou CRRC Times Semiconductor Major Business
 - 9.28.3 Zhuzhou CRRC Times Semiconductor Power Module Packaging Product and Services
 - 9.28.4 Zhuzhou CRRC Times Semiconductor Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.28.5 Zhuzhou CRRC Times Semiconductor Recent Developments/Updates
 - 9.28.6 Zhuzhou CRRC Times Semiconductor Competitive Strengths & Weaknesses
- 9.29 China Resources Microelectronics Limited

- 9.29.1 China Resources Microelectronics Limited Details
- 9.29.2 China Resources Microelectronics Limited Major Business
- 9.29.3 China Resources Microelectronics Limited Power Module Packaging Product and Services
- 9.29.4 China Resources Microelectronics Limited Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
- 9.29.5 China Resources Microelectronics Limited Recent Developments/Updates
- 9.29.6 China Resources Microelectronics Limited Competitive Strengths & Weaknesses
- 9.30 StarPower
 - 9.30.1 StarPower Details
 - 9.30.2 StarPower Major Business
 - 9.30.3 StarPower Power Module Packaging Product and Services
 - 9.30.4 StarPower Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.30.5 StarPower Recent Developments/Updates
 - 9.30.6 StarPower Competitive Strengths & Weaknesses
- 9.31 Yangzhou Yangjie Electronic Technology
 - 9.31.1 Yangzhou Yangjie Electronic Technology Details
 - 9.31.2 Yangzhou Yangjie Electronic Technology Major Business
 - 9.31.3 Yangzhou Yangjie Electronic Technology Power Module Packaging Product and Services
 - 9.31.4 Yangzhou Yangjie Electronic Technology Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.31.5 Yangzhou Yangjie Electronic Technology Recent Developments/Updates
 - 9.31.6 Yangzhou Yangjie Electronic Technology Competitive Strengths & Weaknesses
- 9.32 Guangdong AccoPower Semiconductor
 - 9.32.1 Guangdong AccoPower Semiconductor Details
 - 9.32.2 Guangdong AccoPower Semiconductor Major Business
 - 9.32.3 Guangdong AccoPower Semiconductor Power Module Packaging Product and Services
 - 9.32.4 Guangdong AccoPower Semiconductor Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.32.5 Guangdong AccoPower Semiconductor Recent Developments/Updates
 - 9.32.6 Guangdong AccoPower Semiconductor Competitive Strengths & Weaknesses
- 9.33 Changzhou Galaxy Century Microelectronics
 - 9.33.1 Changzhou Galaxy Century Microelectronics Details
 - 9.33.2 Changzhou Galaxy Century Microelectronics Major Business
 - 9.33.3 Changzhou Galaxy Century Microelectronics Power Module Packaging Product

and Services

9.33.4 Changzhou Galaxy Century Microelectronics Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.33.5 Changzhou Galaxy Century Microelectronics Recent Developments/Updates

9.33.6 Changzhou Galaxy Century Microelectronics Competitive Strengths & Weaknesses

9.34 Hangzhou Silan Microelectronics

9.34.1 Hangzhou Silan Microelectronics Details

9.34.2 Hangzhou Silan Microelectronics Major Business

9.34.3 Hangzhou Silan Microelectronics Power Module Packaging Product and Services

9.34.4 Hangzhou Silan Microelectronics Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.34.5 Hangzhou Silan Microelectronics Recent Developments/Updates

9.34.6 Hangzhou Silan Microelectronics Competitive Strengths & Weaknesses

9.35 Cissoid

9.35.1 Cissoid Details

9.35.2 Cissoid Major Business

9.35.3 Cissoid Power Module Packaging Product and Services

9.35.4 Cissoid Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.35.5 Cissoid Recent Developments/Updates

9.35.6 Cissoid Competitive Strengths & Weaknesses

9.36 SK keyfoundry

9.36.1 SK keyfoundry Details

9.36.2 SK keyfoundry Major Business

9.36.3 SK keyfoundry Power Module Packaging Product and Services

9.36.4 SK keyfoundry Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.36.5 SK keyfoundry Recent Developments/Updates

9.36.6 SK keyfoundry Competitive Strengths & Weaknesses

9.37 PN Junction Semiconductor (Hangzhou)

9.37.1 PN Junction Semiconductor (Hangzhou) Details

9.37.2 PN Junction Semiconductor (Hangzhou) Major Business

9.37.3 PN Junction Semiconductor (Hangzhou) Power Module Packaging Product and Services

9.37.4 PN Junction Semiconductor (Hangzhou) Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)

9.37.5 PN Junction Semiconductor (Hangzhou) Recent Developments/Updates

- 9.37.6 PN Junction Semiconductor (Hangzhou) Competitive Strengths & Weaknesses
- 9.38 United Nova Technology (UNT)
 - 9.38.1 United Nova Technology (UNT) Details
 - 9.38.2 United Nova Technology (UNT) Major Business
 - 9.38.3 United Nova Technology (UNT) Power Module Packaging Product and Services
 - 9.38.4 United Nova Technology (UNT) Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.38.5 United Nova Technology (UNT) Recent Developments/Updates
 - 9.38.6 United Nova Technology (UNT) Competitive Strengths & Weaknesses
- 9.39 InventChip Technology (IVCT)
 - 9.39.1 InventChip Technology (IVCT) Details
 - 9.39.2 InventChip Technology (IVCT) Major Business
 - 9.39.3 InventChip Technology (IVCT) Power Module Packaging Product and Services
 - 9.39.4 InventChip Technology (IVCT) Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.39.5 InventChip Technology (IVCT) Recent Developments/Updates
 - 9.39.6 InventChip Technology (IVCT) Competitive Strengths & Weaknesses
- 9.40 Leadrive Technology
 - 9.40.1 Leadrive Technology Details
 - 9.40.2 Leadrive Technology Major Business
 - 9.40.3 Leadrive Technology Power Module Packaging Product and Services
 - 9.40.4 Leadrive Technology Power Module Packaging Production, Price, Value, Gross Margin and Market Share (2021-2026)
 - 9.40.5 Leadrive Technology Recent Developments/Updates
 - 9.40.6 Leadrive Technology Competitive Strengths & Weaknesses

10 INDUSTRY CHAIN ANALYSIS

- 10.1 Power Module Packaging Industry Chain
- 10.2 Power Module Packaging Upstream Analysis
 - 10.2.1 Power Module Packaging Core Raw Materials
 - 10.2.2 Main Manufacturers of Power Module Packaging Core Raw Materials
- 10.3 Midstream Analysis
- 10.4 Downstream Analysis
- 10.5 Power Module Packaging Production Mode
- 10.6 Power Module Packaging Procurement Model
- 10.7 Power Module Packaging Industry Sales Model and Sales Channels
 - 10.7.1 Power Module Packaging Sales Model
 - 10.7.2 Power Module Packaging Typical Distributors

11 RESEARCH FINDINGS AND CONCLUSION

12 APPENDIX

12.1 Methodology

12.2 Research Process and Data Source

12.3 Disclaimer

List Of Tables

LIST OF TABLES

- Table 1. World Power Module Packaging Production Value by Region (2021, 2025 and 2032) & (USD Million)
- Table 2. World Power Module Packaging Production Value by Region (2021-2026) & (USD Million)
- Table 3. World Power Module Packaging Production Value by Region (2027-2032) & (USD Million)
- Table 4. World Power Module Packaging Production Value Market Share by Region (2021-2026)
- Table 5. World Power Module Packaging Production Value Market Share by Region (2027-2032)
- Table 6. World Power Module Packaging Production by Region (2021-2026) & (K Units)
- Table 7. World Power Module Packaging Production by Region (2027-2032) & (K Units)
- Table 8. World Power Module Packaging Production Market Share by Region (2021-2026)
- Table 9. World Power Module Packaging Production Market Share by Region (2027-2032)
- Table 10. World Power Module Packaging Average Price by Region (2021-2026) & (US\$/Unit)
- Table 11. World Power Module Packaging Average Price by Region (2027-2032) & (US\$/Unit)
- Table 12. Power Module Packaging Major Market Trends
- Table 13. World Power Module Packaging Consumption Growth Rate Forecast by Region (2021 & 2025 & 2032) & (K Units)
- Table 14. World Power Module Packaging Consumption by Region (2021-2026) & (K Units)
- Table 15. World Power Module Packaging Consumption Forecast by Region (2027-2032) & (K Units)
- Table 16. World Power Module Packaging Production Value by Manufacturer (2021-2026) & (USD Million)
- Table 17. Production Value Market Share of Key Power Module Packaging Producers in 2025
- Table 18. World Power Module Packaging Production by Manufacturer (2021-2026) & (K Units)
- Table 19. Production Market Share of Key Power Module Packaging Producers in 2025
- Table 20. World Power Module Packaging Average Price by Manufacturer (2021-2026)

& (US\$/Unit)

Table 21. Global Power Module Packaging Company Evaluation Quadrant

Table 22. World Power Module Packaging Industry Rank of Major Manufacturers, Based on Production Value in 2025

Table 23. Head Office and Power Module Packaging Production Site of Key Manufacturer

Table 24. Power Module Packaging Market: Company Product Type Footprint

Table 25. Power Module Packaging Market: Company Product Application Footprint

Table 26. Power Module Packaging Competitive Factors

Table 27. Power Module Packaging New Entrant and Capacity Expansion Plans

Table 28. Power Module Packaging Mergers & Acquisitions Activity

Table 29. United States VS China Power Module Packaging Production Value Comparison, (2021 & 2025 & 2032) & (USD Million)

Table 30. United States VS China Power Module Packaging Production Comparison, (2021 & 2025 & 2032) & (K Units)

Table 31. United States VS China Power Module Packaging Consumption Comparison, (2021 & 2025 & 2032) & (K Units)

Table 32. United States Based Power Module Packaging Manufacturers, Headquarters and Production Site (States, Country)

Table 33. United States Based Manufacturers Power Module Packaging Production Value, (2021-2026) & (USD Million)

Table 34. United States Based Manufacturers Power Module Packaging Production Value Market Share (2021-2026)

Table 35. United States Based Manufacturers Power Module Packaging Production (2021-2026) & (K Units)

Table 36. United States Based Manufacturers Power Module Packaging Production Market Share (2021-2026)

Table 37. China Based Power Module Packaging Manufacturers, Headquarters and Production Site (Province, Country)

Table 38. China Based Manufacturers Power Module Packaging Production Value, (2021-2026) & (USD Million)

Table 39. China Based Manufacturers Power Module Packaging Production Value Market Share (2021-2026)

Table 40. China Based Manufacturers Power Module Packaging Production, (2021-2026) & (K Units)

Table 41. China Based Manufacturers Power Module Packaging Production Market Share (2021-2026)

Table 42. Rest of World Based Power Module Packaging Manufacturers, Headquarters and Production Site (State, Country)

Table 43. Rest of World Based Manufacturers Power Module Packaging Production Value, (2021-2026) & (USD Million)

Table 44. Rest of World Based Manufacturers Power Module Packaging Production Value Market Share (2021-2026)

Table 45. Rest of World Based Manufacturers Power Module Packaging Production, (2021-2026) & (K Units)

Table 46. Rest of World Based Manufacturers Power Module Packaging Production Market Share (2021-2026)

Table 47. World Power Module Packaging Production Value by Module Type, (USD Million), 2021 & 2025 & 2032

Table 48. World Power Module Packaging Production by Module Type (2021-2026) & (K Units)

Table 49. World Power Module Packaging Production by Module Type (2027-2032) & (K Units)

Table 50. World Power Module Packaging Production Value by Module Type (2021-2026) & (USD Million)

Table 51. World Power Module Packaging Production Value by Module Type (2027-2032) & (USD Million)

Table 52. World Power Module Packaging Average Price by Module Type (2021-2026) & (US\$/Unit)

Table 53. World Power Module Packaging Average Price by Module Type (2027-2032) & (US\$/Unit)

Table 54. World Power Module Packaging Production Value by Package Architecture, (USD Million), 2021 & 2025 & 2032

Table 55. World Power Module Packaging Production by Package Architecture (2021-2026) & (K Units)

Table 56. World Power Module Packaging Production by Package Architecture (2027-2032) & (K Units)

Table 57. World Power Module Packaging Production Value by Package Architecture (2021-2026) & (USD Million)

Table 58. World Power Module Packaging Production Value by Package Architecture (2027-2032) & (USD Million)

Table 59. World Power Module Packaging Average Price by Package Architecture (2021-2026) & (US\$/Unit)

Table 60. World Power Module Packaging Average Price by Package Architecture (2027-2032) & (US\$/Unit)

Table 61. World Power Module Packaging Production Value by Interconnection and Die Attach, (USD Million), 2021 & 2025 & 2032

Table 62. World Power Module Packaging Production by Interconnection and Die

Attach (2021-2026) & (K Units)

Table 63. World Power Module Packaging Production by Interconnection and Die Attach (2027-2032) & (K Units)

Table 64. World Power Module Packaging Production Value by Interconnection and Die Attach (2021-2026) & (USD Million)

Table 65. World Power Module Packaging Production Value by Interconnection and Die Attach (2027-2032) & (USD Million)

Table 66. World Power Module Packaging Average Price by Interconnection and Die Attach (2021-2026) & (US\$/Unit)

Table 67. World Power Module Packaging Average Price by Interconnection and Die Attach (2027-2032) & (US\$/Unit)

Table 68. World Power Module Packaging Production Value by Application, (USD Million), 2021 & 2025 & 2032

Table 69. World Power Module Packaging Production by Application (2021-2026) & (K Units)

Table 70. World Power Module Packaging Production by Application (2027-2032) & (K Units)

Table 71. World Power Module Packaging Production Value by Application (2021-2026) & (USD Million)

Table 72. World Power Module Packaging Production Value by Application (2027-2032) & (USD Million)

Table 73. World Power Module Packaging Average Price by Application (2021-2026) & (US\$/Unit)

Table 74. World Power Module Packaging Average Price by Application (2027-2032) & (US\$/Unit)

Table 75. STMicroelectronics Basic Information, Manufacturing Base and Competitors

Table 76. STMicroelectronics Major Business

Table 77. STMicroelectronics Power Module Packaging Product and Services

Table 78. STMicroelectronics Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 79. STMicroelectronics Recent Developments/Updates

Table 80. STMicroelectronics Competitive Strengths & Weaknesses

Table 81. Infineon Basic Information, Manufacturing Base and Competitors

Table 82. Infineon Major Business

Table 83. Infineon Power Module Packaging Product and Services

Table 84. Infineon Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 85. Infineon Recent Developments/Updates

Table 86. Infineon Competitive Strengths & Weaknesses
Table 87. Wolfspeed Basic Information, Manufacturing Base and Competitors
Table 88. Wolfspeed Major Business
Table 89. Wolfspeed Power Module Packaging Product and Services
Table 90. Wolfspeed Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 91. Wolfspeed Recent Developments/Updates
Table 92. Wolfspeed Competitive Strengths & Weaknesses
Table 93. Rohm Basic Information, Manufacturing Base and Competitors
Table 94. Rohm Major Business
Table 95. Rohm Power Module Packaging Product and Services
Table 96. Rohm Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 97. Rohm Recent Developments/Updates
Table 98. Rohm Competitive Strengths & Weaknesses
Table 99. onsemi Basic Information, Manufacturing Base and Competitors
Table 100. onsemi Major Business
Table 101. onsemi Power Module Packaging Product and Services
Table 102. onsemi Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 103. onsemi Recent Developments/Updates
Table 104. onsemi Competitive Strengths & Weaknesses
Table 105. BYD Semiconductor Basic Information, Manufacturing Base and Competitors
Table 106. BYD Semiconductor Major Business
Table 107. BYD Semiconductor Power Module Packaging Product and Services
Table 108. BYD Semiconductor Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 109. BYD Semiconductor Recent Developments/Updates
Table 110. BYD Semiconductor Competitive Strengths & Weaknesses
Table 111. Microchip (Microsemi) Basic Information, Manufacturing Base and Competitors
Table 112. Microchip (Microsemi) Major Business
Table 113. Microchip (Microsemi) Power Module Packaging Product and Services
Table 114. Microchip (Microsemi) Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 115. Microchip (Microsemi) Recent Developments/Updates

Table 116. Microchip (Microsemi) Competitive Strengths & Weaknesses
Table 117. Mitsubishi Electric Basic Information, Manufacturing Base and Competitors
Table 118. Mitsubishi Electric Major Business
Table 119. Mitsubishi Electric Power Module Packaging Product and Services
Table 120. Mitsubishi Electric Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 121. Mitsubishi Electric Recent Developments/Updates
Table 122. Mitsubishi Electric Competitive Strengths & Weaknesses
Table 123. Semikron Danfoss Basic Information, Manufacturing Base and Competitors
Table 124. Semikron Danfoss Major Business
Table 125. Semikron Danfoss Power Module Packaging Product and Services
Table 126. Semikron Danfoss Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 127. Semikron Danfoss Recent Developments/Updates
Table 128. Semikron Danfoss Competitive Strengths & Weaknesses
Table 129. Fuji Electric Basic Information, Manufacturing Base and Competitors
Table 130. Fuji Electric Major Business
Table 131. Fuji Electric Power Module Packaging Product and Services
Table 132. Fuji Electric Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 133. Fuji Electric Recent Developments/Updates
Table 134. Fuji Electric Competitive Strengths & Weaknesses
Table 135. Navitas (GeneSiC) Basic Information, Manufacturing Base and Competitors
Table 136. Navitas (GeneSiC) Major Business
Table 137. Navitas (GeneSiC) Power Module Packaging Product and Services
Table 138. Navitas (GeneSiC) Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 139. Navitas (GeneSiC) Recent Developments/Updates
Table 140. Navitas (GeneSiC) Competitive Strengths & Weaknesses
Table 141. Toshiba Basic Information, Manufacturing Base and Competitors
Table 142. Toshiba Major Business
Table 143. Toshiba Power Module Packaging Product and Services
Table 144. Toshiba Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 145. Toshiba Recent Developments/Updates

Table 146. Toshiba Competitive Strengths & Weaknesses

Table 147. San'an Optoelectronics Basic Information, Manufacturing Base and Competitors

Table 148. San'an Optoelectronics Major Business

Table 149. San'an Optoelectronics Power Module Packaging Product and Services

Table 150. San'an Optoelectronics Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 151. San'an Optoelectronics Recent Developments/Updates

Table 152. San'an Optoelectronics Competitive Strengths & Weaknesses

Table 153. Littelfuse Basic Information, Manufacturing Base and Competitors

Table 154. Littelfuse Major Business

Table 155. Littelfuse Power Module Packaging Product and Services

Table 156. Littelfuse Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 157. Littelfuse Recent Developments/Updates

Table 158. Littelfuse Competitive Strengths & Weaknesses

Table 159. CETC 55 Basic Information, Manufacturing Base and Competitors

Table 160. CETC 55 Major Business

Table 161. CETC 55 Power Module Packaging Product and Services

Table 162. CETC 55 Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 163. CETC 55 Recent Developments/Updates

Table 164. CETC 55 Competitive Strengths & Weaknesses

Table 165. WeEn Semiconductors Basic Information, Manufacturing Base and Competitors

Table 166. WeEn Semiconductors Major Business

Table 167. WeEn Semiconductors Power Module Packaging Product and Services

Table 168. WeEn Semiconductors Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 169. WeEn Semiconductors Recent Developments/Updates

Table 170. WeEn Semiconductors Competitive Strengths & Weaknesses

Table 171. BASiC Semiconductor Basic Information, Manufacturing Base and Competitors

Table 172. BASiC Semiconductor Major Business

Table 173. BASiC Semiconductor Power Module Packaging Product and Services

Table 174. BASiC Semiconductor Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share

(2021-2026)

Table 175. BASiC Semiconductor Recent Developments/Updates

Table 176. BASiC Semiconductor Competitive Strengths & Weaknesses

Table 177. SemiQ Basic Information, Manufacturing Base and Competitors

Table 178. SemiQ Major Business

Table 179. SemiQ Power Module Packaging Product and Services

Table 180. SemiQ Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 181. SemiQ Recent Developments/Updates

Table 182. SemiQ Competitive Strengths & Weaknesses

Table 183. Diodes Incorporated Basic Information, Manufacturing Base and Competitors

Table 184. Diodes Incorporated Major Business

Table 185. Diodes Incorporated Power Module Packaging Product and Services

Table 186. Diodes Incorporated Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 187. Diodes Incorporated Recent Developments/Updates

Table 188. Diodes Incorporated Competitive Strengths & Weaknesses

Table 189. SanRex Basic Information, Manufacturing Base and Competitors

Table 190. SanRex Major Business

Table 191. SanRex Power Module Packaging Product and Services

Table 192. SanRex Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 193. SanRex Recent Developments/Updates

Table 194. SanRex Competitive Strengths & Weaknesses

Table 195. Alpha & Omega Semiconductor Basic Information, Manufacturing Base and Competitors

Table 196. Alpha & Omega Semiconductor Major Business

Table 197. Alpha & Omega Semiconductor Power Module Packaging Product and Services

Table 198. Alpha & Omega Semiconductor Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 199. Alpha & Omega Semiconductor Recent Developments/Updates

Table 200. Alpha & Omega Semiconductor Competitive Strengths & Weaknesses

Table 201. Bosch Basic Information, Manufacturing Base and Competitors

Table 202. Bosch Major Business

Table 203. Bosch Power Module Packaging Product and Services

Table 204. Bosch Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 205. Bosch Recent Developments/Updates
Table 206. Bosch Competitive Strengths & Weaknesses
Table 207. GE Aerospace Basic Information, Manufacturing Base and Competitors
Table 208. GE Aerospace Major Business
Table 209. GE Aerospace Power Module Packaging Product and Services
Table 210. GE Aerospace Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 211. GE Aerospace Recent Developments/Updates
Table 212. GE Aerospace Competitive Strengths & Weaknesses
Table 213. KEC Corporation Basic Information, Manufacturing Base and Competitors
Table 214. KEC Corporation Major Business
Table 215. KEC Corporation Power Module Packaging Product and Services
Table 216. KEC Corporation Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 217. KEC Corporation Recent Developments/Updates
Table 218. KEC Corporation Competitive Strengths & Weaknesses
Table 219. PANJIT Group Basic Information, Manufacturing Base and Competitors
Table 220. PANJIT Group Major Business
Table 221. PANJIT Group Power Module Packaging Product and Services
Table 222. PANJIT Group Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 223. PANJIT Group Recent Developments/Updates
Table 224. PANJIT Group Competitive Strengths & Weaknesses
Table 225. Nexperia Basic Information, Manufacturing Base and Competitors
Table 226. Nexperia Major Business
Table 227. Nexperia Power Module Packaging Product and Services
Table 228. Nexperia Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 229. Nexperia Recent Developments/Updates
Table 230. Nexperia Competitive Strengths & Weaknesses
Table 231. Vishay Intertechnology Basic Information, Manufacturing Base and Competitors
Table 232. Vishay Intertechnology Major Business
Table 233. Vishay Intertechnology Power Module Packaging Product and Services

Table 234. Vishay Intertechnology Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 235. Vishay Intertechnology Recent Developments/Updates

Table 236. Vishay Intertechnology Competitive Strengths & Weaknesses

Table 237. Zhuzhou CRRC Times Semiconductor Basic Information, Manufacturing Base and Competitors

Table 238. Zhuzhou CRRC Times Semiconductor Major Business

Table 239. Zhuzhou CRRC Times Semiconductor Power Module Packaging Product and Services

Table 240. Zhuzhou CRRC Times Semiconductor Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 241. Zhuzhou CRRC Times Semiconductor Recent Developments/Updates

Table 242. Zhuzhou CRRC Times Semiconductor Competitive Strengths & Weaknesses

Table 243. China Resources Microelectronics Limited Basic Information, Manufacturing Base and Competitors

Table 244. China Resources Microelectronics Limited Major Business

Table 245. China Resources Microelectronics Limited Power Module Packaging Product and Services

Table 246. China Resources Microelectronics Limited Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 247. China Resources Microelectronics Limited Recent Developments/Updates

Table 248. China Resources Microelectronics Limited Competitive Strengths & Weaknesses

Table 249. StarPower Basic Information, Manufacturing Base and Competitors

Table 250. StarPower Major Business

Table 251. StarPower Power Module Packaging Product and Services

Table 252. StarPower Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 253. StarPower Recent Developments/Updates

Table 254. StarPower Competitive Strengths & Weaknesses

Table 255. Yangzhou Yangjie Electronic Technology Basic Information, Manufacturing Base and Competitors

Table 256. Yangzhou Yangjie Electronic Technology Major Business

Table 257. Yangzhou Yangjie Electronic Technology Power Module Packaging Product and Services

Table 258. Yangzhou Yangjie Electronic Technology Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 259. Yangzhou Yangjie Electronic Technology Recent Developments/Updates

Table 260. Yangzhou Yangjie Electronic Technology Competitive Strengths & Weaknesses

Table 261. Guangdong AccoPower Semiconductor Basic Information, Manufacturing Base and Competitors

Table 262. Guangdong AccoPower Semiconductor Major Business

Table 263. Guangdong AccoPower Semiconductor Power Module Packaging Product and Services

Table 264. Guangdong AccoPower Semiconductor Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 265. Guangdong AccoPower Semiconductor Recent Developments/Updates

Table 266. Guangdong AccoPower Semiconductor Competitive Strengths & Weaknesses

Table 267. Changzhou Galaxy Century Microelectronics Basic Information, Manufacturing Base and Competitors

Table 268. Changzhou Galaxy Century Microelectronics Major Business

Table 269. Changzhou Galaxy Century Microelectronics Power Module Packaging Product and Services

Table 270. Changzhou Galaxy Century Microelectronics Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 271. Changzhou Galaxy Century Microelectronics Recent Developments/Updates

Table 272. Changzhou Galaxy Century Microelectronics Competitive Strengths & Weaknesses

Table 273. Hangzhou Silan Microelectronics Basic Information, Manufacturing Base and Competitors

Table 274. Hangzhou Silan Microelectronics Major Business

Table 275. Hangzhou Silan Microelectronics Power Module Packaging Product and Services

Table 276. Hangzhou Silan Microelectronics Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 277. Hangzhou Silan Microelectronics Recent Developments/Updates

Table 278. Hangzhou Silan Microelectronics Competitive Strengths & Weaknesses

Table 279. Cissoid Basic Information, Manufacturing Base and Competitors

Table 280. Cissoid Major Business

Table 281. Cissoid Power Module Packaging Product and Services

Table 282. Cissoid Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 283. Cissoid Recent Developments/Updates

Table 284. Cissoid Competitive Strengths & Weaknesses

Table 285. SK keyfoundry Basic Information, Manufacturing Base and Competitors

Table 286. SK keyfoundry Major Business

Table 287. SK keyfoundry Power Module Packaging Product and Services

Table 288. SK keyfoundry Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 289. SK keyfoundry Recent Developments/Updates

Table 290. SK keyfoundry Competitive Strengths & Weaknesses

Table 291. PN Junction Semiconductor (Hangzhou) Basic Information, Manufacturing Base and Competitors

Table 292. PN Junction Semiconductor (Hangzhou) Major Business

Table 293. PN Junction Semiconductor (Hangzhou) Power Module Packaging Product and Services

Table 294. PN Junction Semiconductor (Hangzhou) Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 295. PN Junction Semiconductor (Hangzhou) Recent Developments/Updates

Table 296. PN Junction Semiconductor (Hangzhou) Competitive Strengths & Weaknesses

Table 297. United Nova Technology (UNT) Basic Information, Manufacturing Base and Competitors

Table 298. United Nova Technology (UNT) Major Business

Table 299. United Nova Technology (UNT) Power Module Packaging Product and Services

Table 300. United Nova Technology (UNT) Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 301. United Nova Technology (UNT) Recent Developments/Updates

Table 302. United Nova Technology (UNT) Competitive Strengths & Weaknesses

Table 303. InventChip Technology (IVCT) Basic Information, Manufacturing Base and Competitors

Table 304. InventChip Technology (IVCT) Major Business

Table 305. InventChip Technology (IVCT) Power Module Packaging Product and

Services

Table 306. InventChip Technology (IVCT) Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 307. InventChip Technology (IVCT) Recent Developments/Updates

Table 308. InventChip Technology (IVCT) Competitive Strengths & Weaknesses

Table 309. Leadrive Technology Basic Information, Manufacturing Base and Competitors

Table 310. Leadrive Technology Major Business

Table 311. Leadrive Technology Power Module Packaging Product and Services

Table 312. Leadrive Technology Power Module Packaging Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 313. Leadrive Technology Recent Developments/Updates

Table 314. Leadrive Technology Competitive Strengths & Weaknesses

Table 315. Global Key Players of Power Module Packaging Upstream (Raw Materials)

Table 316. Global Power Module Packaging Typical Customers

Table 317. Power Module Packaging Typical Distributors

List Of Figures

LIST OF FIGURES

Figure 1. Power Module Packaging Picture

Figure 2. World Power Module Packaging Production Value: 2021 & 2025 & 2032, (USD Million)

Figure 3. World Power Module Packaging Production Value and Forecast (2021-2032) & (USD Million)

Figure 4. World Power Module Packaging Production (2021-2032) & (K Units)

Figure 5. World Power Module Packaging Average Price (2021-2032) & (US\$/Unit)

Figure 6. World Power Module Packaging Production Value Market Share by Region (2021-2032)

Figure 7. World Power Module Packaging Production Market Share by Region (2021-2032)

Figure 8. North America Power Module Packaging Production (2021-2032) & (K Units)

Figure 9. Europe Power Module Packaging Production (2021-2032) & (K Units)

Figure 10. China Power Module Packaging Production (2021-2032) & (K Units)

Figure 11. Japan Power Module Packaging Production (2021-2032) & (K Units)

Figure 12. South Korea Power Module Packaging Production (2021-2032) & (K Units)

Figure 13. Power Module Packaging Market Drivers

Figure 14. Factors Affecting Demand

Figure 15. World Power Module Packaging Consumption (2021-2032) & (K Units)

Figure 16. World Power Module Packaging Consumption Market Share by Region (2021-2032)

Figure 17. United States Power Module Packaging Consumption (2021-2032) & (K Units)

Figure 18. China Power Module Packaging Consumption (2021-2032) & (K Units)

Figure 19. Europe Power Module Packaging Consumption (2021-2032) & (K Units)

Figure 20. Japan Power Module Packaging Consumption (2021-2032) & (K Units)

Figure 21. South Korea Power Module Packaging Consumption (2021-2032) & (K Units)

Figure 22. ASEAN Power Module Packaging Consumption (2021-2032) & (K Units)

Figure 23. India Power Module Packaging Consumption (2021-2032) & (K Units)

Figure 24. Producer Shipments of Power Module Packaging by Manufacturer Revenue (\$MM) and Market Share (%): 2025

Figure 25. Global Four-firm Concentration Ratios (CR4) for Power Module Packaging Markets in 2025

Figure 26. Global Four-firm Concentration Ratios (CR8) for Power Module Packaging Markets in 2025

Figure 27. United States VS China: Power Module Packaging Production Value Market Share Comparison (2021 & 2025 & 2032)

Figure 28. United States VS China: Power Module Packaging Production Market Share Comparison (2021 & 2025 & 2032)

Figure 29. United States VS China: Power Module Packaging Consumption Market Share Comparison (2021 & 2025 & 2032)

Figure 30. United States Based Manufacturers Power Module Packaging Production Market Share 2025

Figure 31. China Based Manufacturers Power Module Packaging Production Market Share 2025

Figure 32. Rest of World Based Manufacturers Power Module Packaging Production Market Share 2025

Figure 33. World Power Module Packaging Production Value by Module Type, (USD Million), 2021 & 2025 & 2032

Figure 34. World Power Module Packaging Production Value Market Share by Module Type in 2025

Figure 35. SiC MOSFET Module

Figure 36. IGBT Module

Figure 37. Intelligent Power Module (IPM)

Figure 38. Others

Figure 39. World Power Module Packaging Production Market Share by Module Type (2021-2032)

Figure 40. World Power Module Packaging Production Value Market Share by Module Type (2021-2032)

Figure 41. World Power Module Packaging Average Price by Module Type (2021-2032) & (US\$/Unit)

Figure 42. World Power Module Packaging Production Value by Package Architecture, (USD Million), 2021 & 2025 & 2032

Figure 43. World Power Module Packaging Production Value Market Share by Package Architecture in 2025

Figure 44. Molded Power Module

Figure 45. Gel-filled Power Module

Figure 46. World Power Module Packaging Production Market Share by Package Architecture (2021-2032)

Figure 47. World Power Module Packaging Production Value Market Share by Package Architecture (2021-2032)

Figure 48. World Power Module Packaging Average Price by Package Architecture (2021-2032) & (US\$/Unit)

Figure 49. World Power Module Packaging Production Value by Interconnection and

Die Attach, (USD Million), 2021 & 2025 & 2032

Figure 50. World Power Module Packaging Production Value Market Share by Interconnection and Die Attach in 2025

Figure 51. Solder Die Attach

Figure 52. Silver Sintering

Figure 53. Copper Sintering

Figure 54. Others

Figure 55. World Power Module Packaging Production Market Share by Interconnection and Die Attach (2021-2032)

Figure 56. World Power Module Packaging Production Value Market Share by Interconnection and Die Attach (2021-2032)

I would like to order

Product name: Global Power Module Packaging Supply, Demand and Key Producers, 2026-2032

Product link: <https://marketpublishers.com/r/GCE9B4E455CEEN.html>

Price: US\$ 4,480.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/GCE9B4E455CEEN.html>